

The Stackup Legend below this is static.  
If you change the stackup, update the Legend.

Layer Name	Order	Copper Thickness	Dielectric
Top Solder Mask	(.GTS)		Solder Resist
Top Layer	(.GTL)	1.4mil	FR-4
Bottom Layer	(.GBL)	1.4mil	FR-4
Bottom Solder Mask	(.GBS)		Solder Resist

**DESIGN INFORMATION**

MIN. TRACK WIDTH: 8 MIL  
 MIN. CLEARANCE: 0.2 mm  
 MIN. VIA PAD SIZE: 24 MIL  
 MINIMUM ANNUAL RING 0.05mm (2MIL) EXTERNAL  
 PER IPC-D-275 CLASS 2 LEVEL C  
 REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

**MATERIAL:**  
 FR-408  FR-4 High Tg  OTHER \_\_\_\_\_  
 THICKNESS:  62 MIL (1.6mm) +/-10%  OTHER \_\_\_\_\_  
 TOLERANCE:  ANSI IPC-6012 TYPE 3 CLASS 2  
 OTHER +/- \_\_\_\_\_  
 BOW & TWIST:  ANSI IPC-6012 TYPE 3 CLASS 2  
 OTHER +/- \_\_\_\_\_

**DRILLING:**  
 REFERENCE:  AS SHOWN  NC\_DRILL FILES  
 PTH MIN COPPER THICKNESS:  1MIL  OTHER \_\_\_\_\_

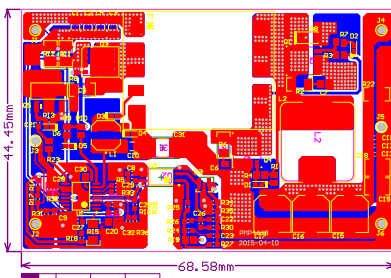
**BOARD FINISH:**  
 SILKSCREEN:  TOP  BOTTOM  
 SILKSCREEN COLOR:  WHITE  OTHER \_\_\_\_\_  
 SOLDER RESIST COLOR:  
 GREEN  BLUE  OTHER \_\_\_\_\_

**SURFACE FINISH:**  IMMERSION GOLD (ENG)  ENEPG  
 IMM. TIN/SILVER OR EQUIV  OTHER \_\_\_\_\_

**ARRAY/PANEL:**  CUT AND TRIM PER MECH LAYER 1  
 N.C. ROUTE  V. SCORE

**CERTIFICATION:** MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:  
 ANSI IPC-A-600F CLASS ->  1  2  3  
 UL 94V-0  RoHS  OTHER PER ORDER

**ADDITIONAL REQUIREMENTS:**  
 MICROSECTION:  YES  
 BARE BOARD ELEC. TEST:  NONE  REQUIRED  PER ORDER  
 MANUFACTURER'S UL:  RAL  METAL  SILK



COMPONENTS MARKED 'DNP' SHOULD NOT BE ORDERED. COMPONENTS MARKED 'DNP' SHOULD NOT BE ORDERED.  
 ASSEMBLY VARIANT: [No Variations]

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**TEXAS INSTRUMENTS**

PROJECT TITLE:  
LM5025A ACF DC-DC 5V/6A Output

DESIGNED FOR:  
Public Release

FILE NAME:  
PMP4468\_PcbDoc

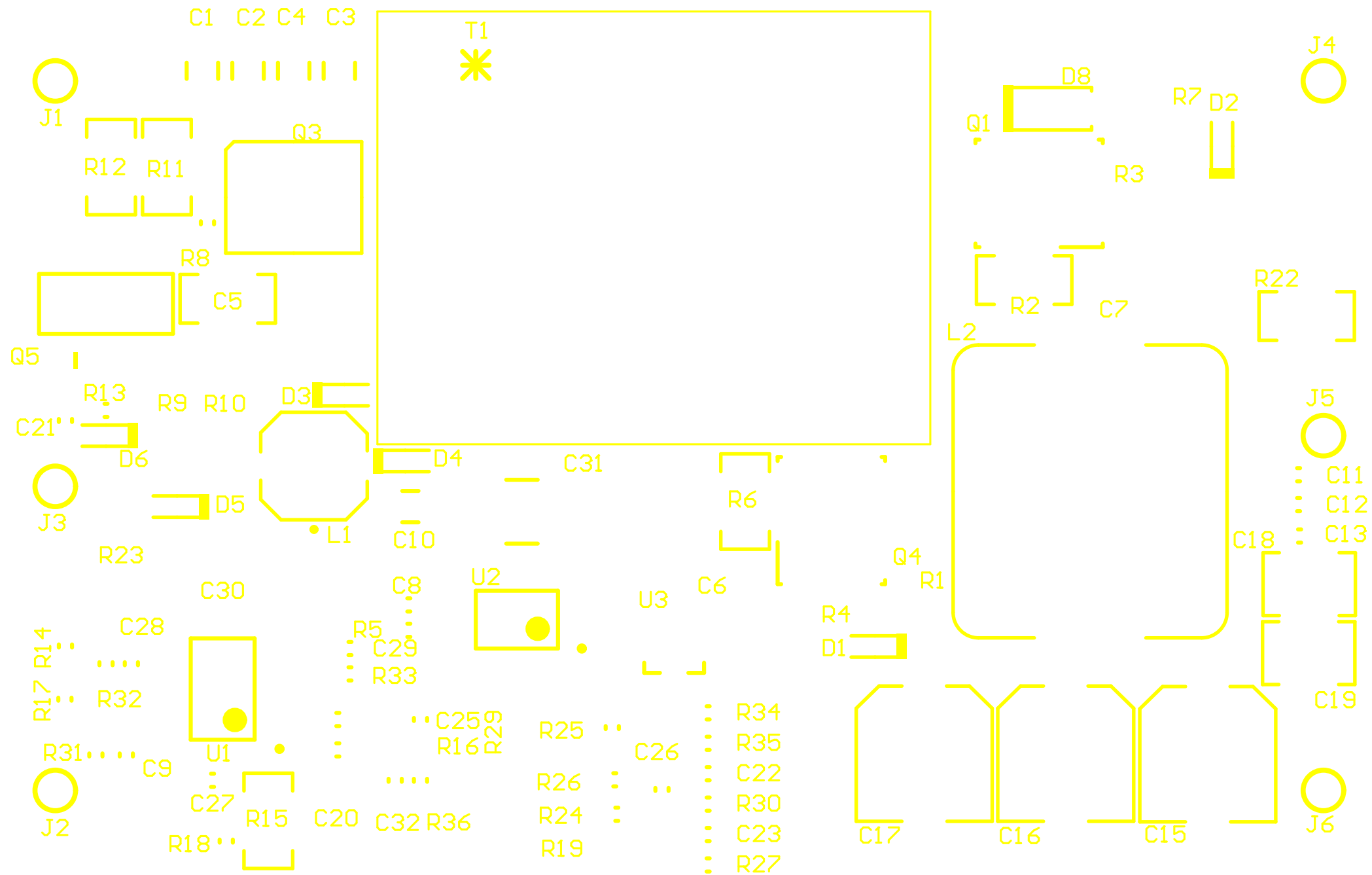
ENGINEER:  
Jason Yu

LAYOUT BY:  
Jason Yu

SCALE: 0.72

ALTIUM DESIGNER VERSION:  
14.3.17.42447

ADDITIONAL COMMENTS	BOARD #:	DATE:	DESIGNER:	DATE:	DESIGNER:
LAYER NAME = Top Layer	1	2	3	4	5
LAYER NAME = Bottom Layer	1	2	3	4	5





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